

Appl. No. 10/649,454
Docket No.: H1799-00221
Reply to Office Action dated June 2, 2004

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously Presented) A heat pipe system comprising:
a heat transfer block including at least two clip channels; and,
a heat pipe coupled to the heat transfer block by a clip that is received in said at least two clip channels.
2. (Original) The heat pipe system of claim 1, wherein the clip includes a main surface and two side surfaces disposed substantially orthogonal to the main surface.
3. (Original) The heat pipe system of claim 1, wherein the heat transfer block includes at least one clip channel disposed therein for receiving the clip.
4. (Cancelled)
5. (Original) The heat pipe system of claim 1, wherein the heat transfer block includes at least one heat pipe channel disposed therein for receiving the heat pipe.

Appl. No. 10/649,454
Docket No.: H1799-00221
Reply to Office Action dated June 2, 2004

6. (Original) The heat pipe system of claim 5, wherein the heat pipe includes a main portion and a pinchoff portion, wherein the pinchoff portion is disposed in the heat pipe channel.

7. (Original) The heat pipe system of claim 5, wherein the heat pipe is coupled to the heat pipe channel by solder.

8. (Original) The heat pipe system of claim 5, wherein the heat pipe is coupled to the heat pipe channel by epoxy.

9. (Original) The heat pipe system of claim 5, wherein the heat pipe is coupled to the heat pipe channel by friction.

10. (Original) The heat pipe system of claim 5, wherein the heat pipe is coupled to the heat pipe channel by at least one fastener.

11. (Original) The heat pipe system of claim 2, wherein the heat transfer block includes at least one clip channel disposed therein for receiving the clip, such that the two side surfaces of the clip are disposed in the at least one clip channel.

Appl. No. 10/649,454
Docket No.: H1799-00221
Reply to Office Action dated June 2, 2004

12. (Original) The heat pipe system of claim 11, wherein the clip is coupled to the at least two clip channels by solder.

13. (Original) The heat pipe system of claim 11, wherein the clip is coupled to the at least two clip channels by epoxy.

14. (Original) The heat pipe system of claim 11, wherein the clip is coupled to the at least two clip channels by friction.

15. (Original) The heat pipe system of claim 11, wherein the heat pipe is coupled to the heat pipe channel by at least one fastener.

16. (Original) The heat pipe system of claim 2, wherein the heat transfer block includes at least two clip channels disposed therein for receiving the clip, such that the two side surfaces of the clip are disposed in the at least two clip channels.

17. (Original) The heat pipe system of claim 16, wherein the clip is coupled to the at least two clip channels by solder.

18. (Original) The heat pipe system of claim 16, wherein the clip is coupled to the at least two clip channels by epoxy.

Appl. No. 10/649,454
Docket No.: H1799-00221
Reply to Office Action dated June 2, 2004

19. (Original) The heat pipe system of claim 16, wherein the clip is coupled to the at least two clip channels by friction.

20. (Original) The heat pipe system of claim 16, wherein the heat pipe is coupled to the heat pipe channel by at least one fastener.

21. (Original) The heat pipe system of claim 1, wherein the clip includes a top surface and bottom surface with at least two tabs extending orthogonally from the bottom surface.

22. (Original) The heat pipe system of claim 21, wherein the heat transfer block includes at least two channels for receiving the at least two tabs in the clip.

23. (Original) The heat pipe system of claim 1, wherein the clip extends substantially across an entire top surface of the heat transfer block.

24. (Original) A computer comprising:
at least one electronic component;
a heat transfer block disposed adjacent to the at least one electronic component; and,

Appl. No. 10/649,454
Docket No.: H1799-00221
Reply to Office Action dated June 2, 2004

a heat pipe coupled to the heat transfer block by a clip.

25.-29. (Cancelled)